# 2.5V Drive Nch+Nch MOS FET UM6K1N

### Structure

Silicon N-channel MOS FET

### ●Features

- 1) Two 2SK3018 transistors in a single UMT package.
- 2) The MOS FET elements are independent, eliminating mutual interference.
- 3) Mounting cost and area can be cut in half.
- 4) Low On-resistance.
- 5) Low voltage drive (2.5V drive) makes this device ideal for portable equipment.

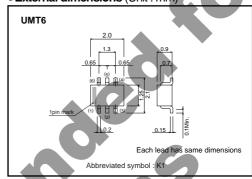
### Applications

Interfacing, switching (30V, 100mA)

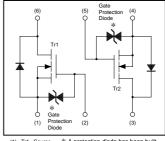
### Packaging specifications

Туре	Package	Taping	
	Code	TN	
	Basic ordering unit (pieces)	3000	
UM6K1N		70	

### ●External dimensions (Unit : mm)



# ●Inner circuit



- A protection diode has been built in between the gate and the source to protect against static electricity when the product is in use.
  Use the protection circuit when cated welfages are exceeded.

## ● Absolute maximum ratings (Ta=25°C)

<It is the same ratings for Tr1 and Tr2.:</p>

Parameter		Symbol	Limits	Unit
Drain-source voltage		V <sub>DSS</sub>	30	V
Gate-source voltage		V <sub>GSS</sub>	±20	V
Drain current	Continuous	$I_{D}$	±100	mA
Drain current	Pulsed	I <sub>DP</sub> *1	±400	mA
Total power dissipation		P <sub>D</sub> *2	150	mW
Channel temperature		Tch	150	°C
Range of storage temperature		Tstg	-55 to +150	°C

- \*1 Pw≤10µs, Duty cycle≤1%
- \*2 With each pin mounted on the recommended lands.

### ●Thermal resistance

Parameter	Symbol	Limits	Unit
Channel to ambient	Rth(ch-a)*	833	°C / W / TOTAL
Charmer to ambient	Kin(cn-a)	1042	°C/W/ELEMENT

<sup>\*</sup> With each pin mounted on the recommended lands.

### ●Electrical characteristics (Ta=25°C)

<It is the same characteristics for Tr1 and Tr2.>

Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions
Gate-source leakage	Igss	-	-	±1	μА	Vgs=±20V, Vps=0V
Drain-source breakdown voltage	V(BR) DSS	30	_	_	V	ID= 10μA, VGS=0V
Zero gate voltage drain current	IDSS	-	_	1.0	μΑ	VDS= 30V, VGS=0V
Gate threshold voltage	V <sub>GS (th)</sub>	0.8	_	1.5	V	$V_{DS} = 3V$ , $I_{D} = 100 \mu A$
Static drain-source on-state resistance	Dec.	-	5	8	Ω	I <sub>D</sub> = 10mA, V <sub>GS</sub> = 4V
	R <sub>DS</sub> (on)	-	7	13	Ω	I <sub>D</sub> = 1mA, V <sub>GS</sub> = 2.5V
Forward transfer admittance	Yfs	20	_	_	mS	I <sub>D</sub> = 10mA, V <sub>DS</sub> = 3V
Input capacitance	Ciss	_	13	_	pF	V <sub>DS</sub> = 5V
Output capacitance	Coss	_	9	_	pF	V <sub>GS</sub> =0V
Reverse transfer capacitance	Crss	_	4	_	pF	f=1MHz
Turn-on delay time	t <sub>d (on)</sub>	-	15	_	ns	Vpp≒5V
Rise time	tr	-	35	_	ns	ID= 10mA
Turn-off delay time	t <sub>d (off)</sub>	-	80	_	ns	Vgs= 5V R <sub>L</sub> =500Ω
Fall time	t <sub>f</sub>	_	80	_	ns	R <sub>G</sub> =10Ω

### •Electrical characteristic curves

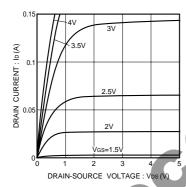


Fig.1 Typical Output Characteristics

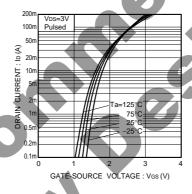


Fig.2 Typical Transfer Characteristics

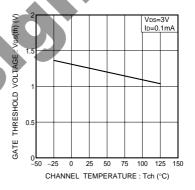


Fig.3 Gate Threshold Voltage vs. Channel Temperature

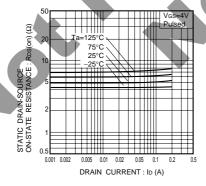


Fig.4 Static Drain-Source On-State Resistance vs. Drain Current ( I )

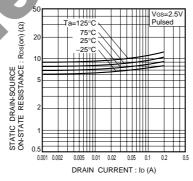


Fig.5 Static Drain-Source On-State Resistance vs. Drain Current (II)

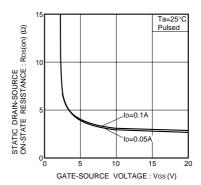


Fig.6 Static Drain-Source On-State Resistance vs. Gate-Source Voltage

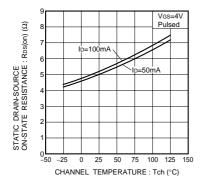


Fig.7 Static Drain-Source On-State Resistance vs. Channel Temperature

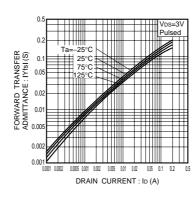


Fig.8 Forward Transfer Admittance vs. Drain Current

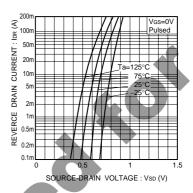


Fig.9 Reverse Drain Current vs. Source-Drain Voltage (I)

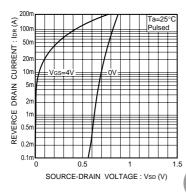


Fig.10 Reverse Drain Current vs. Source-Drain Voltage (II)

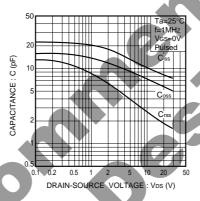


Fig.11 Typical Capacitance vs. Drain-Source Voltage

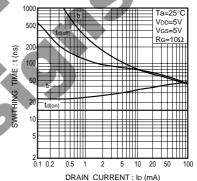


Fig.12 Switching Characteristics

### •Switching characteristics measurement circuit

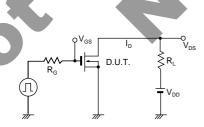


Fig.13 Switching Time Test Circuit

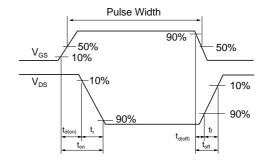


Fig.14 Switching Time Waveforms

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